Overview

HP EliteBook 840 Aero G8 Notebook PC



- 1. Ambient Light Sensor (Optional)
- 2. Internal Microphones (2)
- 3. Webcam LED (Optional)
- 4. Camera Shutter
- 5. IR Camera (Optional)
- 6. IR Camera LEDs (Optional)

- Left
- 7. Glass Clickpad
- 8. Smartcard Reader (Optional)
- 9. Audio Combo Jack
- **10.** SuperSpeed USB Type-A 5Gbps signaling rate
- 11. SuperSpeed USB Type-A 5Gbps signaling rate (1 Charging)
- 12. Nano Security Lock Slot (Lock sold separately)



Overview



Right

- 1. Power Button Key
- 2. Power Connector
- 3. HDMI 2.0b Port (Cable not included)
- 4. Thunderbolt[™] 4 with USB4[™]Type-C[®] 40Gbps signaling rate (USB Power Delivery, DisplayPort[™] 1.4)¹

1.SuperSpeed USB 20Gbps is not available with Thunderbolt™ 4.

- Thunderbolt[™] 4 with USB4[™] Type-C[®] 40Gbps signaling rate (USB Power Delivery, DisplayPort[™] 1.4)¹
- 6. SIM Card Slot (Optional)
- 7. Touch Fingerprint Sensor (Select models)



Overview

AT A GLANCE

- Windows 11 Pro, other Windows OS or FreeDOS preinstalled
- Starting at less than 2.50 lbs (1.13 kg)¹ you can take the HP EliteBook 840 Aero anywhere without feeling weighed down
- Premium ultraslim design with precision-crafted and recycled magnesium chassis for a premium look and feel
- 11th Generation Intel[®] Core[™] i5, i7 Processors up to four-core
- Designed to support all HP docking options including the HP Universal Dock G5 (Sold separately)
- Featuring the redesigned quiet HP Keyboard with the HP Programmable key and backlit options
- Innovative world-facing third mic improves inbound ambient noise cancellation while 360-degree mic pick-up allows everyone to clearly hear and be heard
- Optional ultrabright displays with ambient light sensor
- Choice of displays:
 - 35.6 cm (14") diagonal FHD IPS Anti-Glare LED-backlit, 250 nits, 45% NTSC
 - 35.6 cm (14") diagonal FHD IPS Anti-Glare LED-backlit non-touch 400 nits, 72% NTSC
 - 35.6cm (14") diagonal FHD IPS Anti-Glare LED-backlit non-touch, 1000 nits, 100% sRGB with HP Sure View Reflect 35.6cm (14") diagonal FHD IPS Anti-Glare On-Cell LED-backlit touch, 250 nits, 45% NTSC
- Enterprise grade security with HP Sure Sense, HP Sure Start Gen 6, HP Privacy Camera, HP Sure View Reflect, HP Sure Run Gen4, HP Sure Recover Gen4 with Embedded Reimaging, HP Sure Click, SmartCard Reader and Touch Fingerprint reader
- Connectivity with optional Intel[®] XMM[™] 7360 LTE-Advanced Cat 9, Qualcomm[®] Snapdragon[™] X55 5G ModemCat 20 and Thunderbolt[™] Docking (Dock sold separately)
- Supports fast charging (50% in 30 minutes) with no impact on battery recharge cycles
- Choice of solid state drives up to 2 TB and DDR4 memory up to 64 GB
- Undergoes MIL-STD 810H tests²
- Intel[®] Iris[®] X^e Graphics

1. WWAN, SureView Reflect, 250n panel, 2xDIMMs, Smart Card Slot and EMMC not available on configurations starting at less than 2.5 lbs on HP EliteBook 840 Aero G8.

2. MIL-STD 810H is not intended to demonstrate fitness of U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.

NOTE: See important legal disclosures for all listed specs in their respective features sections.

PRODUCT NAME

HP EliteBook 840 Aero G8 Notebook PC

OPERATING SYSTEM

PreinstalledWindows 11 Pro 2
Windows 11 Pro Education 2
Windows 11 Home – HP recommends Windows 11 Pro for business 2
Windows 11 Home Single Language – HP recommends Windows 11 Pro for business 2
Windows 11 Pro (Windows 11 Enterprise available with a Volume Licensing Agreement) 2
Windows 10 Pro 1,2
Windows 10 Pro Education 1,2
Windows 10 Home – HP recommends Windows 11 Pro for business 1,2
Windows 10 Home Single Language – HP recommends Windows 11 Pro for business 1,2
Windows 10 Home Single Language – HP recommends Windows 11 Pro for business 1,2
Windows 10 Home Single Language – HP recommends Windows 11 Pro for business 1,2
Windows 10 Home Single Language – HP recommends Windows 11 Pro for business 1,2
Windows 10 Pro (Windows 10 Enterprise available with a Volume Licensing Agreement) 1,2
FreeDOS

1. Device comes with Windows 10 and a free Windows 11 upgrade or may be preloaded with Windows 11. Upgrade timing may vary by device. Features and app availability may vary by region. Certain features require specific hardware (see Windows 11 Specifications).

2. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

PROCESSORS

Intel[®] Core[™] i7-1165G7 processor (Up to 4.7 GHz with Intel[®] Turbo Boost Technology, 12 MB L3 cache, 4 cores) ^{3,4,5,6} Intel[®] Core[™] i7-1185G7 (Up to 4.8 GHz with Intel[®] Turbo Boost Technology, 12 MB L3 cache, 4 cores), supports Intel[®] vPro[®] Technology ^{3,4,5,6}

Intel[®] Core[™] i5-1135G7 (2.4 GHz base frequency, up to 4.2 GHz with Intel[®] Turbo Boost Technology, 8 MB L3 cache, 4 cores) ^{3,4,5,6}

Intel[®] Core[™] i5-1145G7 (Up to 4.4 GHz with Intel[®] Turbo Boost Technology, 8 MB L3 cache, 4 cores), supports Intel[®] vPro[®] Technology ^{3,4,5,6}

Processor Family

11th Generation Intel[®] Core[™] i7 processor (i7-1165G7)⁶

11th Generation Intel[®] Core[™] i7 processor (i7-1185G7)⁶

11th Generation Intel[®] Core[™] i5 processor (i5-1135G7)⁶

11th Generation Intel[®] Core[™] i5 processor (i5-1145G7)⁶

3.Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

4.Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.5. Intel[®] Turbo Boost performance varies depending on hardware, software and overall system configuration. See



http://www.intel.com/technology/turboboost for more information.

6. In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.

CHIPSET

Chipset is integrated with processor.

GRAPHICS

Integrated Intel[®] Iris[®] X^e Graphics⁷

Supports

Support HD decode, DX12, HDMI 2.0b, HDCP 2.38

7. Intel[®] Iris[®] Xe Graphics capabilities require system to be configured with Intel[®] Core[™] i5 or i7 processors and dual channel memory. Intel[®] Iris[®] Xe Graphics with Intel[®] Core[™] i5 or 7 processors and single channel memory will only function as UHD graphics.

8. HDMI cable sold separately.

DISPLAY

Non-Touch

35.56 cm (14") diagonal FHD bent, anti-glare UMA eDP, 250 nits, 45% NTSC for HD + IR Camera for WWAN 4G (1920 x 1080) ^{9,10}

35.56 cm (14") diagonal FHD bent, anti-glare UMA eDP, 250 nits, 45% NTSC for HD + IR Camera for WWAN 5G (1920 x 1080) ^{9,10}

35.56 cm (14") diagonal FHD bent, anti-glare UMA eDP+PSR, 400 nits, 100% sRGB, Low Power Ambient Light Sensor for HD + IR Camera (1920 x 1080) ^{9,10}

35.56 cm (14") diagonal FHD bent, anti-glare UMA eDP+PSR, 400 nits, 100% sRGB, Low Power Ambient Light Sensor for HD + IR Camera for WWAN 4G (1920 x 1080) ^{9,10}

35.56 cm (14") diagonal FHD bent, anti-glare UMA eDP+PSR, 400 nits, 100% sRGB, Low Power Ambient Light Sensor for HD + IR Camera for WWAN 5G (1920 x 1080) ^{9,10}

35.56 cm (14") diagonal FHD bent, anti-glare UMA eDP+PSR, 1000 nits, 100% sRGB with HP Sure View Reflect integrated privacy screen, Ambient Light Sensor for HD + IR Camera (1920 x 1080) ^{9,10,11,12}

35.56 cm (14") diagonal FHD bent, anti-glare UMA eDP+PSR, 1000 nits, 72% NTSC with HP Sure View Reflect integrated privacy screen, Ambient Light Sensor for HD + IR Camera for WWAN 4G (1920 x 1080) ^{9,10,11,12}

35.56 cm (14") diagonal FHD bent, anti-glare UMA eDP+PSR, 1000 nits, 72% NTSC with HP Sure View Reflect integrated privacy screen, Ambient Light Sensor for HD + IR Camera for WWAN 5G (1920 x 1080) ^{9,10,11,12}

Touch

35.56 cm (14") diagonal FHD bent, anti-glare UMA eDP, 250 nits, 45% NTSC for HD + IR Camera for WWAN 4G Touch on Panel (1920 x 1080) ^{9,10,11,12}



Technical Specifications

HDMI 2.0¹³

Support resolution up to 4K @60 Hz

9. FHD/HD content required to view FHD/HD images.

10. Resolutions are dependent upon monitor capability, and resolution and color depth settings.

11. HP Sure View integrated privacy screen is an optional feature that must be configured at purchase and is designed to function in landscape orientation.

12. Actual brightness will be lower with touchscreen or Sure View.

13. HDMI cable sold separately.

Docking station model (Sold separately)	Total number of supported displays (incl. the notebook) display)	Max resolutions supported for DP 1.4 hosts with DSC	Dock Connectors	Technical limitations / additional information For more details refer to HP Dock QuickSpecs http://h20195.www2.hp.com/v2/GetDocume nt.aspx?docname=c04168358 All information below applies to platforms running DP 1.4 with DSC
HP Thunderbolt Dock G2	Max number of displays = 4	Dual 8K@ 60Hz in high res mode	2xDP, 1xVGA, 1xTB, 1xUSB-C alt-mode	Max displays = 4 with max resolution of 5K@ 30Hz running Thunderbolt host Max resolution possible is dual 8K displays @ 60Hz running Thunderbolt host or running a non-Thunderbolt host in High Resolution mode The highest resolution for dual displays running a non-Thunderbolt host in Multi- function mode is one 5K dual cable (using both DP ports) + one 4K on USB-C DP port
HP USB-C Dock G5	3	Dual 5K@ 30Hz + 1 4K UHD (multi- function mode)	1xHDMI, 2xDP	Three maximum displays supported are two 5K@ 30 Hz on DP ports plus one 4K UHD@ 30 Hz on HDMI in Multi-function mode Highest resolution with dual displays is two 8K@ 60Hz host in High Resolution mode The highest resolution for running a non- Thunderbolt host in Multi-function mode is a single 5K dual cable (using both DP ports) + one 4K on HDMI port

Technical Specifications

HP USB-C/A Universal Dock G2	3	Triple 4K UHD@ 60Hz	1xHDMI, 2xDP	In High Resolution, mode the max available is one display. This dock's best use case is triple display. The best resolution for dual display is two 4K UHD@ 60Hz Highest triple displays resolution available is three 4KUHD @60Hz using both DP and 1 HDMI port. Best single display is with High Resolution mode using HDMI port.
HP USB-C Travel Dock G2	1	Single 4K@ 30 Hz 4960 x 2160 (via HDMI)	1xHDMI, 1xVGA	Single external display using either HDMI or VGA

STORAGE AND DRIVES

Primary M.2 Storage

2 TB PCIe[®] Gen3x4 NVMe[™] M.2 SSD TLC¹⁴ 1 TB PCIe[®] Gen3x4 NVMe[™] M.2 SSD TLC¹⁴ 512 GB PCIe[®] Gen3x4 NVMe[™] M.2 SSD TLC¹⁴ 256 GB PCIe[®] Gen3x4 NVMe[™] M.2 SSD TLC¹⁴ 512 GB PCIe[®] NVMe[™] Value M.2 SSD¹⁴ 256 GB PCIe[®] NVMe[™] Value M.2 SSD¹⁴ 512 GB PCIe[®]Gen 3x4 NVMe[™] M.2 SED TLC OPAL2¹⁴ 256 GB PCIe[®] Gen3x4 NVMe[™] M.2 SED TLC OPAL2¹⁴ 256 GB PCIe[®] Gen3x4 NVMe[™] M.2 SED TLC OPAL2¹⁴ 512 GB Intel[®] PCIe[®] NVMe[™] QLC M.2 SSD with 32 GB Intel[®] Optane[™] memory H10^{14,15}

14 For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10 and 11) is reserved for system recovery software.

15. Intel[®] Optane[™] H10 memory system acceleration does not replace or increase the DRAM in your system. Requires 8th Gen or higher Intel[®] Core[™] processor, BIOS version with Intel[®] Optane[™] supported, Windows 10 64-bit, and an Intel[®] Rapid Storage Technology (Intel[®] RST) driver.



MEMORY

Maximum Memory

64 GB DDR4-3200 SDRAM¹⁶

Memory

64 GB DDR4-3200 SDRAM (2 x 32 GB)¹⁶ 32 GB DDR4-3200 SDRAM (2 x 16 GB)¹⁶ 16 GB DDR4-3200 SDRAM (2 x 8 GB)¹⁶ 16 GB DDR4-3200 SDRAM (1 x 16 GB)¹⁶ 8 GB DDR4-3200 SDRAM (1 x 8 GB)¹⁶

Memory Slots

2 SODIMM DDR4 SODIMMS, system runs at 3200 Supports Dual Channel Memory

16. Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.



NETWORKING/COMMUNICATIONS

WLAN

Intel® Dual Band Wi-Fi® 6 AX201 802.11a/b/g/n/ac/ax (2x2) WLAN and Bluetooth® 5 Combo, vPro^{®17, 18} Intel® Dual Band Wi-Fi® 6 AX201 802.11a/b/g/n/ac/ax (2x2) WLAN and Bluetooth® 5 Combo, non-vPro^{®17}

WWAN

Intel[®] XMM[™] 7360 LTE-Advanced Cat 9 ¹⁹ Qualcomm[®] Snapdragon[™] X55 5G ModemCat 20 ²⁰

Miracast

Native Miracast Support²¹

Near Field Communications (NFC) Module ²² HP Module with NXP NFC Controller NPC300 12C NCI

17. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs.

18. For full Intel[®] vPro[™] functionality, Windows, a vPro supported processor, vPro enabled chipset, vPro enabled WLAN card and discrete TPM 2.0 are required. See https://www.intel.com/content/www/us/en/architecture-and-technology/vpro/vpro-platform-general.html

19. WWAN module is an optional feature, requires factory configuration and requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. LTE not available on all products, in all regions.

20. 5G module is an optional feature that must be configured at purchase. AT&T and T-Mobile networks supported in the U.S. Module designed for 5G networks as carriers deploy Evolved-Universal Terrestrial Radio Access New Radio Dual Connectivity (ENDC) with both 100Mhz of 5G NR and LTE channel bandwidth, using 256QAM 4x4 as defined by 3GPP, requires activation and separately purchased service contract. Check with service provider for coverage and availability in your area. Connection, upload and download speeds will vary due to network, location, environment, network conditions, and other factors. 5G not available on all products, in all regions. Backwards compatible to 4G LTE and 3G HSPA technologies. 5G module planned to be available in select countries, where carrier supported.

21. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming.

22. Sold separately or as an optional feature.



AUDIO/MULTIMEDIA

Audio

Audio by Bang & Olufsen 2 Integrated stereo speakers Integrated microphone (3-Mic Array) World- Facing microphone

Speaker Power 2W/4ohm Per speaker

Camera 720p HD+IR camera^{9,22}

Sensors Ambient light sensor Hall Sensor HP Tamper Lock²³

9. FHD/HD content required to view FHD/HD images.

22. Sold separately or as an optional feature.

23. HP Tamper Lock must be enabled by the customer or your administrator.

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard²⁴

HP Premium Keyboard – spill-resistant, backlit keyboard

Pointing Device

Clickpad with multi-touch gesture support, taps enabled as default Microsoft Precision Touchpad Default Gestures Support

Function Keys

- F1 Display Switching
- F2 Blank or Privacy
- F3 Brightness Down
- F4 Brightness Up
- F5 Audio Mute
- F6 Volume Down
- F7 Volume Up
- F8 Mic Mute
- F9 Blank or Backlit Toggle
- F10 Insert
- F11 Airplane Mode
- F12 HP Command Center (Programmable Key)

Print Screen

Power Button (with LED)



Technical Specifications

Hidden Function Keys

Fn+R - Break Fn+S - Svs Ra Fn+C - Scroll Lock

24. Keyboards are made from up to 50% post-consumer recycled plastic.

SOFTWARE AND SECURITY

Preinstalled Software

- BIOS
- HP BIOSphere Gen6²⁵ HP Drive Lock & Automatic Drive Lock **BIOS Update via Network** HP Secure Erase²⁶ Absolute Persistence Module²⁷ **HP LAN-Wireless Protection** USB enable/disable (via BIOS)

Software

HP Easy Clean 55 HP Connection Optimizer²⁸ **HP Hotkey Support myHP** HP Support Assistant²⁹ HP QuickDrop ³⁰ **HP Noise Cancellation Software** Touchpoint Customizer for Commercial **HP** Notifications **HP Privacy Settings HP Wireless Button Driver HP Power Manager** Tile App³¹ **HP PC Hardware Diagnostics Windows** Microsoft Defender 32 Buy Microsoft Office (Sold separately) HP Smart Support⁵⁶

Manageability Features

HP Driver Packs (download)³³ HP Manageability Integration Kit Gen4 (download)³⁴ HP System Software Manager (SSM) (download) HP Client Catalog (download) HP Client Management Script Library (download) HP Image Assistant (download)



Security Management

HP Client Security Manager Gen7³⁵ Pre-boot Authentication HP Wolf Pro Security Edition³⁶ HP Sure Click³⁷ HP Sure Start Gen 6³⁸ HP Sure Sense³⁹ HP Sure Admin⁴⁰ HP Sure Recover Gen4⁴¹ HP Sure Run Gen4⁴² Touch Fingerprint Sensor (Select models) ⁴³

Is the BIOS on this notebook ISO/IEC 19678:2015 (formerly NIST 800-147) compliant?: Yes

UEFI version: 2.7

Class: Class 3

25. HP BIOSphere Gen6 is available on select HP Pro and Elite PCs. Features may vary depending on the platform and configurations.

26. HP Secure Erase for the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel[®] Optane[™].

27. Absolute firmware module is shipped turned off and can only be activated with the purchase a license subscription and full activation of the software agent. License subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. Certain conditions apply. For full details visit: https://www.absolute.com/about/legal/agreements/absolute/

28. HP Connection Optimizer requires Windows 10.

29. HP Support Assistant requires Windows and Internet access.

30. HP Quick Drop requires Internet access and Windows 10 PC preinstalled with HP QuickDrop app and either an Android device (phone or tablet) running Android 7 or higher with the Android HP QuickDrop app, and /or an iOS device (phone or tablet) running iOS 12 or higher with the iOS HP QuickDrop app.

31.Tile is an optional feature that must be configured at the factory and requires Windows 10. Some features require optional subscription to Tile Premium. Tile application for Windows 10 available for download from the Windows Store. Mobile phone app available for download from App Store and Google Play. Requires iOS 11 and greater or Android 6.0 and greater see https://support.thetileapp.com/hc/en-us/articles/200424778 for more information. HP Tile will function as long as the PC has battery power.

32. Windows Defender Opt in and internet connection required for updates.

33. HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.

34. HP Manageability Integration Kit can be downloaded from

http://www8.hp.com/us/en/ads/clientmanagement/overview.html.

35. HP Client Security Manager Gen7 requires Windows and is available on the select HP Elite and Pro PCs.

36. HP Wolf Pro Security Edition (including HP Sure Click Pro and HP Sure Sense Pro) is available preloaded on select SKUs and, depending on the HP product purchased, includes a paid 1-year or 3-year license. The HP Wolf Pro Security Edition software is licensed under the license terms of the HP Wolf Security Software - End-User license Agreement (EULA) that can be found at: https://support.hp.com/us-en/document/ish_3875769-3873014-16 as that EULA is modified by the following: "7. Term. Unless otherwise terminated earlier pursuant to the terms contained in this EULA, the license for the HP Wolf Pro Security Edition (HP Sure Sense Pro and HP Sure Click Pro) is effective upon activation and will continue for either a twelve (12) month or thirty-six (36) month license term ("Initial Term"). At the end of the Initial Term you may either (a) purchase a renewal license for the HP Wolf Pro Security Edition from HP.com, HP Sales or an HP Channel Partner, or (b) continue using the standard versions of HP Sure Click and HP Sure Sense at no additional cost with no future software updates or HP



Support.

37.HP Sure Click requires Windows 10 Pro or Enterprise. See https://bit.ly/2PrLT6A_SureClick for complete details 38. HP Sure Start Gen6 is available on select HP PCs and requires Windows 10.

39. HP Sure Sense is available on select HP PCs and is not available with Windows10 Home.

40. HP Sure Admin requires Windows 10, HP BIOS, HP Manageability Integration Kit from

http://www.hp.com/go/clientmanagement and HP Sure Admin Local Access Authenticator smartphone app from the Android or Apple store.

41. HP Sure Recover Gen4 is available on select HP PCs and requires an open network connection. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data.

42.HP Sure Run Gen4 is available on select Windows 10 based HP Pro, Elite and Workstation PCs with select Intel® or AMD processors.

43. HP Fingerprint sensor is an optional feature that must be configured at purchase.

55. HP Easy Clean requires Windows 10 RS3 and will disable the keyboard, touchscreen, and clickpad only. Ports are not disabled. See user guide for cleaning instructions. Expected availability March 2020.

56. HP Smart Support is available to commercial customers through your HP Service Representative and HP Factory Configuration Services; or it can be downloaded at: http://www.hp.com/smart-support. HP Smart Support automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights.



Technical Specifications

SMART CARD READER

Smart Card Reader (Optional) Smart card standard Dimensions (L x W x H) Smart Card support Smart Card Interface PC/SC 2.0 for Windows smart card standard 0.41x 0.08 x 0.32 in (10.5 x 2 x 8.2 mm) ISO 7816 Class A and AB smart cards Smart Card Interface with T = 0 and T = 1 support Support I2C memory card, SLE4418, SLE4428, SLE4432, SLE4442, SLE4436, SLE5536, SLE6636, AT88SC1608, AT45D041 card and AT45DB041 card via external EEPROM

POWER

Power Supply

HP Smart 65 W External AC power adapter⁵⁶ HP Smart 65 W EM External AC power adapter⁵⁶ HP Smart 65 W USB Type-C adapter⁵⁶ HP Smart 45 W External AC power adapter⁵⁶ HP Smart 45 W External AC power adapter, 2-prong (Japan only)⁵⁶

Power Cord

2-wire plug - 1.0m 3-wire plug - 1.0m

Primary Battery

HP Long Life 3-cell, 53 Wh Polymer^{44,45} Supports HP Fast Charge (Up to 50% in 30 minutes)⁴⁶

Battery Life

Up to 14 hours and 45 minutes⁴⁷

Battery Weight

0.45 lb 0.205 kg

56. Availability may vary by country.

44. Battery is internal and not replaceable by customer. Serviceable by warranty.

45. Actual battery Watt-hours (Wh) will vary from design capacity. Battery capacity will naturally decrease with shelf life, time, usage, environment, temperature, system configuration, loaded apps, features, power management settings and other factors.

46. Supports HP Fast Charge with 65W AC Adapter. Recharges the battery up to 50% within 30 minutes when the system is off or in standby mode. Power adapter with a minimum capacity of 65 watts is required. After charging has reached 50% capacity, charging will return to normal. Charging time may vary +/-10% due to System tolerance.

47. Windows 10 MM18 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See http://www.bapco.com for additional details.



WEIGHTS & DIMENSIONS

Product Weight Non-Touch Starting at 2.48 lb (1.13 kg)⁴⁸ Touch Starting at 2.88 lb (1.31 kg)⁴⁸

Product Dimensions (W x D x H) 12.73 x 8.45 x 0.71in 323.37 x 214.59 x 17.95mm

48. Weight will vary by configuration.

PORTS/SLOTS

Ports

2 Thunderbolt[™] 4 with USB4[™] Type-C[®] 40Gbps signaling rate (USB Power Delivery, DisplayPort[™] 1.4) ⁵⁴
2 SuperSpeed USB Type-A 5Gbps signaling rate (1 Charging)
1 HDMI 2.0b⁴⁹
1 Headphone/microphone combo
1 4.5 mm AC power
1 nano SIM card slot⁵⁰
1 Smartcard reader (Optional)
1 Nano Security Lock Slot (Lock sold separately)

49. HDMI cable sold separately.

50. All units have a SIM card slot and icon but units that do not support WWAN are shipped with a non-removable SIM slot plug.

54. SuperSpeed USB 20Gbps is not available with Thunderbolt[™] 4.



SERVICE AND SUPPORT

1-year and 3-year limited warranties and 90 day software limited warranty options depending on country. Batteries have a default one year limited warranty except for HP Long Life batteries which will follow the one or three year warranty of the platfor. Refer to http://www.hp.com/support/batterywarranty/ for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc.⁵¹

51. HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit http://www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.



Technical Specifications

SYSTEM UNIT

Nominal Operating Voltage	19.5V
Average Operating Power	1.825W
Integrated graphics	Yes
Discrete Graphics	N/A
Max Operating Power	UMA < 45W
Temperature	
Operating	32° to 95° F (0° to 35° C)
Non-operating	41° to 95° F (5° to 35° C) (writing optical)
Relative Humidity	
Operating	10% to 90%, non-condensing
Non-operating Shock	5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature
Operating	40 G, 2 ms, half-sine
Non-operating	200 G, 2 ms, half-sine
Random Vibration	
Operating	0.75 grms
Non-operating	1.50 grms
Altitude (unpressurized)	
Operating	-50 to 10,000 ft (-15.24 to 3,048 m)
Non-operating	-50 to 40,000 ft (-15.24 to 12,192 m)
Planned Industry Standard	
Certifications UL	
	Yes
CSA FSC Compliance	Yes
FCC Compliance	Yes
ENERGY STAR®	ENERGY STAR [®] Select models ⁵²
EPEAT®	EPEAT [®] Gold in United States ⁵³
ICES	Yes
Australia /	Yes
NZ A-Tick Compliance	Yes
CCC	Yes
Japan VCCI Compliance	Yes
KC	Yes
BSMI	Yes
CE Marking Compliance BNCI or BELUS	Yes
CIT	Yes
EAC (Russia)	Yes
	Yes
Saudi Arabian Compliance (ICCP)	Yes
SABS	Yes
	Deals 040 Asia CO Natabash DC that any ENEDCY CTAD® availifiad any ide

52. Configurations of the HP EliteBook 840 Aero G8 Notebook PC that are ENERGY STAR[®] qualified are identified as HP EliteBook 840 Aero G8 Notebook PC ENERGY STAR[®] on HP websites and on http://www.energystar.gov.



Technical Specifications

53. Based on US EPEAT[®] registration according to IEEE 1680.1-2018 EPEAT[®]. Status varies by country. Visit http://www.epeat.net for more information.

DISPLAYS

1. Actual brightness will be lower with touchscreen or Sure View. Note: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

Panel LCD 14 inch FHD (1920x1080) Anti-Glare WLED UWVA 45percent cg 250nits eDP 1.2 w/o PSR bent NWBZ	Outline Dimensions (W x H) Active Area Weight Diagonal Size Thickness Interface Surface Treatment Touch Enabled Contrast Ratio Refresh Rate Brightness Pixel Resolution Format Backlight Color Gamut Coverage Color Depth Viewing Angle	316.17 x 186.4 mm (max) (w/ PCB) 309.37 x 174.02 mm 300 g (max) 14.0 inch 3.0 mm/ 5.0 mm (PCB) (max) eDP 1.2 Anti-Glare No 600:1 60 Hz 250 nits 1920 x 1080 (FHD) RGB Stripe LED NTSC 45% 6 bits (Hi FRC supportive w/ condition to enable) UWVA 85/85/85/85
Panel LCD 14 inch FHD (1920x1080) Anti-Glare WLED UWVA 45percent cg 250nits eDP 1.2 w/o PSR bent Touch on Panel NWBZ	Outline Dimensions (W x H) Active Area Weight Diagonal Size Thickness Interface Surface Treatment Touch Enabled Contrast Ratio Refresh Rate Brightness Pixel Resolution Format Backlight Color Gamut Coverage Color Depth Viewing Angle	316.17 x 186.4 mm (max) (w/ PCB) 309.37 x 174.02 mm 305 g (max) 14.0 inch 3.0 mm/ 5.0 mm (PCB) (max) eDP 1.2 Anti-Glare On-cell Yes 600:1 60 Hz 250 nits ¹ 1920 x 1080 (FHD) RGB Stripe LED NTSC 45% 6 bits (Hi FRC supportive w/ condition to enable) UWVA 85/85/85/85



	Outline Dimensions (W x H)	315.07 x 186.6 mm (max)
(1920x1080) Anti-Glare WLED UWVA sRGB 100percent cg	Active Area	309.37 X 174.02 mm
400nits eDP	Weight	200 g (max)
1.4+PSR2 bent LP NB2X	Diagonal Size	14.0 inch
	Thickness	2.0 mm/4.0 mm (w/PCB) (max)
	Interface	eDP 1.4
	Surface Treatment	Anti-Glare
	Touch Enabled	No
	Contrast Ratio	1200:1
	Refresh Rate	60 Hz
	Brightness	400 nits
	Pixel Resolution	1920 x 1080 (FHD)
	Format	RGB Stripe
	Backlight	LED
	Color Gamut Coverage	sRGB 100% (NTSC 72%)
	Color Depth	8 bits
	Viewing Angle	UWVA 85/85/85/85
Panel LCD 14-in FHD (1920x1080)	Outline Dimensions (W x H x D)	314.612 x 185.33 mm (max.)
Anti-Glare WLED UWVA 100% sRGB	Outline Dimensions (W x H x D) Active Area	314.612 x 185.33 mm (max.) 309.312 x 173.99 mm
Anti-Glare WLED UWVA 100% sRGB 1000nits eDP 1.4+PSR HP Sure View		
Anti-Glare WLED UWVA 100% sRGB	Active Area	309.312 x 173.99 mm
Anti-Glare WLED UWVA 100% sRGB 1000nits eDP 1.4+PSR HP Sure View	Active Area Weight	309.312 x 173.99 mm 230 g (max.)
Anti-Glare WLED UWVA 100% sRGB 1000nits eDP 1.4+PSR HP Sure View	Active Area Weight Diagonal Size	309.312 x 173.99 mm 230 g (max.) 14.0"
Anti-Glare WLED UWVA 100% sRGB 1000nits eDP 1.4+PSR HP Sure View	Active Area Weight Diagonal Size Thickness	309.312 x 173.99 mm 230 g (max.) 14.0" 3.9 mm (max.)
Anti-Glare WLED UWVA 100% sRGB 1000nits eDP 1.4+PSR HP Sure View	Active Area Weight Diagonal Size Thickness Interface	309.312 x 173.99 mm 230 g (max.) 14.0" 3.9 mm (max.) eDP
Anti-Glare WLED UWVA 100% sRGB 1000nits eDP 1.4+PSR HP Sure View	Active Area Weight Diagonal Size Thickness Interface Surface Treatment	309.312 x 173.99 mm 230 g (max.) 14.0" 3.9 mm (max.) eDP Anti-glare (AG)
Anti-Glare WLED UWVA 100% sRGB 1000nits eDP 1.4+PSR HP Sure View	Active Area Weight Diagonal Size Thickness Interface Surface Treatment Touch Enabled	309.312 x 173.99 mm 230 g (max.) 14.0" 3.9 mm (max.) eDP Anti-glare (AG) No
Anti-Glare WLED UWVA 100% sRGB 1000nits eDP 1.4+PSR HP Sure View	Active Area Weight Diagonal Size Thickness Interface Surface Treatment Touch Enabled Contrast Ratio	309.312 x 173.99 mm 230 g (max.) 14.0" 3.9 mm (max.) eDP Anti-glare (AG) No 1500:1
Anti-Glare WLED UWVA 100% sRGB 1000nits eDP 1.4+PSR HP Sure View	Active Area Weight Diagonal Size Thickness Interface Surface Treatment Touch Enabled Contrast Ratio Refresh Rate	309.312 x 173.99 mm 230 g (max.) 14.0" 3.9 mm (max.) eDP Anti-glare (AG) No 1500:1 60 Hz
Anti-Glare WLED UWVA 100% sRGB 1000nits eDP 1.4+PSR HP Sure View	Active Area Weight Diagonal Size Thickness Interface Surface Treatment Touch Enabled Contrast Ratio Refresh Rate Brightness	309.312 x 173.99 mm 230 g (max.) 14.0" 3.9 mm (max.) eDP Anti-glare (AG) No 1500:1 60 Hz 1000 nits ¹
Anti-Glare WLED UWVA 100% sRGB 1000nits eDP 1.4+PSR HP Sure View	Active Area Weight Diagonal Size Thickness Interface Surface Treatment Touch Enabled Contrast Ratio Refresh Rate Brightness Pixel Resolution	309.312 x 173.99 mm 230 g (max.) 14.0" 3.9 mm (max.) eDP Anti-glare (AG) No 1500:1 60 Hz 1000 nits ¹ 1920 x 1080 (FHD)
Anti-Glare WLED UWVA 100% sRGB 1000nits eDP 1.4+PSR HP Sure View	Active Area Weight Diagonal Size Thickness Interface Surface Treatment Touch Enabled Contrast Ratio Refresh Rate Brightness Pixel Resolution Format	309.312 x 173.99 mm 230 g (max.) 14.0" 3.9 mm (max.) eDP Anti-glare (AG) No 1500:1 60 Hz 1000 nits ¹ 1920 x 1080 (FHD) RGB
Anti-Glare WLED UWVA 100% sRGB 1000nits eDP 1.4+PSR HP Sure View	Active Area Weight Diagonal Size Thickness Interface Surface Treatment Touch Enabled Contrast Ratio Refresh Rate Brightness Pixel Resolution Format Backlight	309.312 x 173.99 mm 230 g (max.) 14.0" 3.9 mm (max.) eDP Anti-glare (AG) No 1500:1 60 Hz 1000 nits ¹ 1920 x 1080 (FHD) RGB LED
Anti-Glare WLED UWVA 100% sRGB 1000nits eDP 1.4+PSR HP Sure View	Active Area Weight Diagonal Size Thickness Interface Surface Treatment Touch Enabled Contrast Ratio Refresh Rate Brightness Pixel Resolution Format Backlight Color Gamut Coverage	309.312 x 173.99 mm 230 g (max.) 14.0" 3.9 mm (max.) eDP Anti-glare (AG) No 1500:1 60 Hz 1000 nits ¹ 1920 x 1080 (FHD) RGB LED 100% sRGB



STORAGE

For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10 and 11) is reserved for system recovery software.

SSD 1TB 2280 PCle-3x4	Form Factor	M.2 2280	
NVMe Three Layer Cell	Capacity	1 TB	
single-sided	NAND Type	TLC	
	Height	0.09 in (2.3 mm)	
	Width	0.87 in (22 mm)	
	Weight	0.02 lb (10 g)	
	Interface	PCIe NVMe Gen3X4	
	Maximum Sequential Read	Up to 3100 ~ 3500 MB/s	
	Maximum Sequential Write	Up to 2700 ~ 3037 MB/s	
	Logical Blocks	2,000,409,264	
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
	Features	ATA Security; TRIM; L1.2	
SSD 256GB 2280 M2 PCIe-	Form Factor	M.2 2280	
3x4 SS NVMe TLC	Capacity	256 GB	
	NAND Type	TLC	
	Height	0.09 in (2.3 mm)	
	Width	0.87 in (22 mm)	
	Weight	0.02 lb (10 g)	
	Interface	PCIe NVMe Gen3X4	
	Maximum Sequential Read	Up to 2800 ~ 3500 MB/s	
	Maximum Sequential Write	Up to 1600 ~ 2200 MB/s	
	Logical Blocks	500,118,192	
	Logical Blocks		
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	

		N 2 2200
SSD 256GB 2280 PCIe NVMe Value	Form Factor	M.2 2280
	Capacity	256 GB
	NAND Type	
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen3X2
	Maximum Sequential Read	Up to 2100 ~ 2400 MB/s
	Maximum Sequential Write	Up to 950 ~ 1400 MB/s
	Logical Blocks	500,118,192
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security (Option); TRIM; L1.2
SSD 256GB 2280 PCIe-3x4	Form Factor	N
NVMe Self Encrypted OPAL2	Capacity	M.2 2280
Three Layer Cell	NAND Type	256 GB
	Height	TLC
	Width	0.09 in (2.3 mm)
	Weight	0.87 in (22 mm)
	Interface	0.02 lb (10 g)
		PCIe NVMe Gen3X4
	Maximum Sequential Read	
	Maximum Sequential Write	Up to 2800 ~ 3500 MB/s
		Up to 1663 ~ 2200 MB/s
	Logical Blocks	500,118,192
	Operating Temperature	
		32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security (Option); TCG Opal 2.0; TRIM; L1.2
SSD 2TB 2280 PCIe-3x4	Form Factor	M.2 2280
SSD 21B 2280 PCIe-3x4 NVMe Three Layer Cell	Capacity	2 TB
single-sided	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen3X4
	Maximum Sequential Read	Up to 3100 ~ 3500 MB/s



	Maximum Sequential Write	Up to 2800 ~ 3000 MB/s
	Logical Blocks	3,907,029,168
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security; TRIM; L1.2
SSD 512GB 2280 M2 PCIe-	Form Factor	M.2 2280
3x4 SS NVMe TLC	Capacity	512 GB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen3X4
	Maximum Sequential Read	Up to 3100 ~ 3500 MB/s
	Maximum Sequential Write	Up to 2100 ~ 2956 MB/s
	Logical Blocks	1,000,215,215
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security; TRIM; L1.2
SSD 512GB 2280 PCIe NVMe	Form Factor	M.2 2280
Value	Capacity	512 GB
	NAND Type	Value
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen3X2
	Maximum Sequential Read	Up to 1500 ~ 2400 MB/s
	Maximum Sequential Write	Up to 1000 ~ 1750 MB/s
	Logical Blocks	1,000,215,215
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security (Option); TRIM; L1.2



	Farma Faratan	
SSD 512GB 2280 PCIe-3x2x2 NVMe+SSD 32GB 3D Xpoint	Form Factor	M.2 2280
	Capacity	512 GB
	NAND Type	QLC+3D XPoint
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen3X2X2
	Maximum Sequential Read	
		Up to 2400 MB/s
	Maximum Sequential Write	
		Up to 1300 MB/s
	Logical Blocks	1,000,215,215
	Operating Temperature	
		32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security; TRIM; L1.2
SSD 512GB 2280 PCIe-3x4	Form Factor	M.2 2280
NVMe Self Encrypted OPAL2	Capacity	M.2 2280 512 GB
	Capacity NAND Type	
NVMe Self Encrypted OPAL2	Capacity NAND Type Height	512 GB
NVMe Self Encrypted OPAL2	Capacity NAND Type Height Width	512 GB TLC
NVMe Self Encrypted OPAL2	Capacity NAND Type Height Width Weight	512 GB TLC 0.09 in (2.3 mm)
NVMe Self Encrypted OPAL2	Capacity NAND Type Height Width Weight Interface	512 GB TLC 0.09 in (2.3 mm) 0.87 in (22 mm)
NVMe Self Encrypted OPAL2	Capacity NAND Type Height Width Weight	512 GB TLC 0.09 in (2.3 mm) 0.87 in (22 mm) 0.02 lb (10 g)
NVMe Self Encrypted OPAL2	Capacity NAND Type Height Width Weight Interface	512 GB TLC 0.09 in (2.3 mm) 0.87 in (22 mm) 0.02 lb (10 g)
NVMe Self Encrypted OPAL2	Capacity NAND Type Height Width Weight Interface	512 GB TLC 0.09 in (2.3 mm) 0.87 in (22 mm) 0.02 lb (10 g) PCle NVMe Gen3X4
NVMe Self Encrypted OPAL2	Capacity NAND Type Height Width Weight Interface Maximum Sequential Read	512 GB TLC 0.09 in (2.3 mm) 0.87 in (22 mm) 0.02 lb (10 g) PCle NVMe Gen3X4
NVMe Self Encrypted OPAL2	Capacity NAND Type Height Width Weight Interface Maximum Sequential Read	512 GB TLC 0.09 in (2.3 mm) 0.87 in (22 mm) 0.02 lb (10 g) PCle NVMe Gen3X4 Up to 3100 ~ 3500 MB/s
NVMe Self Encrypted OPAL2	Capacity NAND Type Height Width Weight Interface Maximum Sequential Read Maximum Sequential Write	512 GB TLC 0.09 in (2.3 mm) 0.87 in (22 mm) 0.02 lb (10 g) PCIe NVMe Gen3X4 Up to 3100 ~ 3500 MB/s Up to 2400 ~ 2956 MB/s
NVMe Self Encrypted OPAL2	Capacity NAND Type Height Width Weight Interface Maximum Sequential Read Maximum Sequential Write	512 GB TLC 0.09 in (2.3 mm) 0.87 in (22 mm) 0.02 lb (10 g) PCIe NVMe Gen3X4 Up to 3100 ~ 3500 MB/s Up to 2400 ~ 2956 MB/s
NVMe Self Encrypted OPAL2	Capacity NAND Type Height Width Weight Interface Maximum Sequential Read Maximum Sequential Write	512 GB TLC 0.09 in (2.3 mm) 0.87 in (22 mm) 0.02 lb (10 g) PCIe NVMe Gen3X4 Up to 3100 ~ 3500 MB/s Up to 2400 ~ 2956 MB/s 1,000,215,215

NETWORKING

Intel® Wi-Fi 6 ¹ AX201 and Bluetooth® 5 (802.11ax 2x2, vPro®, supporting gigabit file transfer speeds) ⁵ (vPro®)	Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11h IEEE 802.11i IEEE 802.11r IEEE 802.11v
	Interoperability	Features Wi-Fi 6 technology
	Frequency Band	•802.11b/g/n/ax 2.402 – 2.482 GHz •802.11a/n/ac/ax 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz
	Data Rates	 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: max 300Mbps 802.11ac : 1733Mbps 802.11ax : max 2.4Gbps
	Modulation	Direct Sequence Spread Spectrum OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
	Security ³	 IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification WPA3 certification IEEE 802.11i WAPI
	Network Architecture	Ad-hoc (Peer to Peer)
	Models Roaming	Infrastructure (Access Point Required) IEEE 802.11 compliant roaming between access points
	Output Power ²	 802.11b : +17dBm minimum 802.11g : +16dBm minimum 802.11a : +17dBm minimum 802.11n HT20(2.4GHz) : +14dBm minimum 802.11n HT40(2.4GHz) : +13dBm minimum 802.11n HT20(5GHz) : +14dBm minimum 802.11n HT40(5GHz) : +13dBm minimum 802.11n HT40(5GHz) : +13dBm minimum



	 802.11ac VHT160(5GHz) : +10dBm minimum 802.11ax HE40(2.4GHz) : +12dBm minimum 802.11ax HE80(5GHz) : +10dBm minimum 802.11ax HE160(5GHz) : +10dBm minimum
Power Consumption	 Transmit mode: 2.0 W Receive mode: 1.6 W Idle mode (PSP) 180 mW (WLAN Associated) Idle mode: 50 mW (WLAN unassociated) Connected Standby/Modern Standby: 10mW Radio disabled: 8 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity ⁴	 802.11b, 1Mbps : -93.5dBm maximum 802.11b, 11Mbps : -84dBm maximum 802.11a/g, 6Mbps : -86dBm maximum 802.11a/g, 54Mbps : -72dBm maximum 802.11n, MCS07 : -67dBm maximum 802.11n, MCS15 : -64dBm maximum 802.11ac, MCS0(VHT80) : -84dBm maximum 802.11ac, MCS9(VHT80) : -59dBm maximum 802.11ac, MCS9(VHT80) : -59dBm maximum 802.11ac, MCS9(VHT160) : -58.5dBm maximum 802.11ax, MCS11(HE40): -57dBm maximum 802.11ax, MCS11(HE160): -53.5dBm maximum
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard with CNVi Interface
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm
Weight	1. Type 2230: 2.8 g 2. Type 126: 1.3 g
Operating Voltage	3.3v +/- 9%
Temperature	Operating 14° to 158° F (–10° to 70° C) Non-operating –40° to 176° F (–40° to 80° C)
Humidity	Operating 10% to 90% (non-condensing) Non-operating 5% to 95% (non-condensing)
Altitude	Operating 0 to 10,000 ft (3,048 m) Non-operating 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF LED White – Radio ON
HP Integrated Module with Bluetooth 4.0/4.1/4.2/	5.0/5.1/5.2 Wireless Technology
Bluetooth Specification	
Frequency Band	2402 to 2480 MHz

Bluetooth Specification	4.0/4.1/4.2/5.0/5.1/5.2 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Signaling Data Rate	Legacy: 3 Mbps signaling data rate ¹ 2.17 Mbps BLE: 1 Mbps signaling data rate ¹ 0.2 Mbps 1. Actual throughput may vary.



Technical Specifications

	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels
	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 9.5 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Bluetooth Software Supported Link Topology	Microsoft Windows Bluetooth Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP) BT5.2 ESR9/10 Compliance LE Advertisement Extensions Channel Selection Algo Limited High Duty Cycle Non-Connectable Advertising 2Mbps LE LE Long Range
Security & Manageability	Intel® vPro® support with appropriate Intel® chipset components

1. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs.

2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel

12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

3. Check latest software/driver release for updates on supported security features.

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

5. Wi-Fi 6 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.



Intel® Wi-Fi 6 ¹ AX201 and Bluetooth® 5 (802.11ax 2x2, non-vPro®, supporting gigabit file transfer speeds) ⁵ non-vPro®		IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v
	Interoperability	Features Wi-Fi 6 technology
	Frequency Band	•802.11b/g/n/ax 2.402 – 2.482 GHz •802.11a/n/ac/ax 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz
	Data Rates	 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: max 300Mbps 802.11ac : 1733Mbps 802.11ax : max 2.4Gbps
	Modulation	Direct Sequence Spread Spectrum OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
	Security ³	 IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification WPA3 certification IEEE 802.11i WAPI
	Network Architecture	Ad-hoc (Peer to Peer)
	Models	Infrastructure (Access Point Required)
	Roaming Output Power ²	IEEE 802.11 compliant roaming between access points • 802.11b : +17dBm minimum • 802.11g : +16dBm minimum • 802.11a : +17dBm minimum • 802.11n HT20(2.4GHz) : +14dBm minimum • 802.11n HT40(2.4GHz) : +13dBm minimum • 802.11n HT20(5GHz) : +14dBm minimum • 802.11n HT40(5GHz) : +13dBm minimum • 802.11ac VHT80(5GHz) : +10dBm minimum



	• 802.11ax HE40 • 802.11ax HE80	60(5GHz) : +10dBm minimum)(2.4GHz) : +12dBm minimum)(5GHz) : +10dBm minimum ;0(5GHz) : +10dBm minimum
Power Consumption		.6 W 180 mW (WLAN Associated) W (WLAN unassociated) dby 10mW
Power Management		ress compliant power management It power saving mode
Receiver Sensitivity ⁴	 802.11b, 11Mb 802.11a/g, 6Ml 802.11a/g, 54N 802.11a, MCS0 802.11ac, MCS1 802.11ac, MCS1 802.11ac, MCS2 	s : -93.5dBm maximum ps : -84dBm maximum bps : -86dBm maximum 4bps : -72dBm maximum 7 : -67dBm maximum 5 : -64dBm maximum 0(VHT80) : -84dBm maximum 9(VHT80) : -59dBm maximum 9(VHT160) : -58.5dBm maximum 11(HE40): -57dBm maximum 11(HE80): -54dBm maximum 11(HE160): -53.5dBm maximum
Antenna type	enclosure Two embedded o	ntenna with spatial diversity, mounted in the display dual band 2.4/5 GHz antennas are provided to the card to IMO communications and Bluetooth communications
Form Factor	PCI-Express M.2	MiniCard with CNVi Interface
Dimensions		3 x 22.0 x 30.0 mm 57 x 12.0 x 16.0 mm
Weight	1. Type 2230: 2.8 2. Type 126: 1.3	-
Operating Voltage	3.3v +/- 9%	
Temperature	Operating Non-operating	14° to 158° F (–10° to 70° C) –40° to 176° F (–40° to 80° C)
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)
Altitude	Operating Non-operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Rac LED Off – Radio (



HP Integrated Module with	Bluetooth 4.0/4.1/4.2/5.0/5	5.1 Wireless Technoloav
	Bluetooth Specification	4.0/4.1/4.2/5.0/5.1/5.2 Compliant
	Frequency Band	2402 to 2480 MHz
	Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
	Signaling Data Rate	Legacy: 3 Mbps signaling data rate ¹ 2.17 Mbps BLE: 1 Mbps signaling data rate ¹ 0.2 Mbps 1. Actual throughput may vary.
		Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels
		Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
	Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 9.5 dBm for BR and EDR.
	Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
	Bluetooth Software Supported Link Topology	Microsoft Windows Bluetooth Software
	Power Management	Microsoft Windows ACPI, and USB Bus Support
	Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
	Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
	Bluetooth Software Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy LE Privacy 1.2 -Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP) BT5.2 ESR9/10 Compliance LE Advertisement Extensions Channel Selection Algo Limited High Duty Cycle Non-Connectable Advertising 2Mbps LE LE Long Range

1. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs.2. The FCC has declared as of September 1, 2014 products that



utilize passive scanning on channel

12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

3. Check latest software/driver release for updates on supported security features.

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a

packet error rate of 10% for 802.11a/g (OFDM modulation).

5. Wi-Fi 6 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.

Qualcomm[®] Snapdragon™ X55 5G Modem ¹ Technology/ Operating bands WCDMA/HSDPA/HSUPA/HSPA+ operating bands: Band 1: 1920 to 1980 MHz (UL), 2110 to 2170 MHz (DL) Band 2: 1850 to 1910 MHz (UL), 1930 to 1990 MHz (DL) Band 4: 1710 to 1755 MHz (UL). 2110 to 2155 MHz (DL) Band 5: 824 to 849 MHz (UL), 869 to 894 MHz (DL) Band 6: 830 to 840 MHz (UL), 875 to 885 MHz (DL) Band 8: 880 to 915 MHz (UL), 925 to 960 MHz (DL) Band 9: 1750 to 1785 MHz(UL), 1845to 1880 MHz (DL) Band 19: 830 to 845 MHz (UL). 875 to 890 MHz (DL) LTE FDD/TDD operating bands: Band 1: 1920 to 1980 MHz (UL), 2110 to 2170 MHz (DL) Band 2: 1850 to 1910 MHz (UL), 1930 to 1990 MHz (DL) Band 3: 1710 to 1785 MHz (UL), 1805 to 1880 MHz (DL) Band 4: 1710 to 1755 MHz (UL), 2110 to 2155 MHz (DL) Band 5: 824 to 849 MHz (UL), 869 to 894 MHz (DL) Band 7: 2500 to 2570 MHz (UL), 2620 to 2690 MHz (DL) Band 8: 880 to 915 MHz (UL), 925 to 960 MHz (DL) Band 12: 699 to 716 MHz (UL), 729 to 746 MHz (DL) Band 13: 777 to 787 MHz (UL), 746 to 756 MHz (DL) Band 14: 788 to 798 MHz (UL), 758 to 768 MHz (DL) Band 17: 704 to 716 MHz (UL), 734 to 746 MHz (DL) Band 18: 815 to 830 MHz (UL), 860 to 875 MHz (DL) Band 19: 830 to 845 MHz (UL), 875 to 890 MHz (DL) Band 20: 832 to 862 MHz (UL), 791 to 821 MHz (DL) Band 25: 1850 to 1915 MHz (UL), 1930 to 1995 MHz (DL) Band 26: 814 to 849 MHz (UL), 859 to 894 MHz (DL) Band 28: 703 to 748 MHz (UL), 758 to 803 MHz (DL) Band 29: 717 to 728 MHz (DL) Band 30: 2305 to 2315 MHz (UL) 2350 to 2360 MHz (DL) Band 34: 2010 to 2025 MHz (UL/DL) Band 38: 2570 to 2620 MHz (UL/DL) Band 39: 1880 to 1920 MHz (UL/DL) Band 40: 2300 to 2400 MHz (UL/DL) Band 41: 2496 to 2690 MHz (UL/DL) Band 42: 3400 to 3600 MHZ (UL/DL) Band 46: 5150 to 5925 MHZ (DL) Band 48: 3550 to 3700 MHZ (UL/DL) Band 66: 1710 to 1800 MHz (UL), 2110 to 2200 MHz (DL) 5GNR Sub 6GHZ: n1: 1920 to 1980 MHz (UL). 2110 to 2170 MHz (DL) n2: 1850 to 1910 MHz (UL), 1930 to 1990 MHz (DL) n3: 1710 to 1785 MHz (UL), 1805 to 1880 MHz (DL) n5: 824 to 849 MHz (UL), 869 to 894 MHz (DL) n7: 2500 to 2570 MHz (UL), 2620 to 2690 MHz (DL) n8: 880 to 915 MHz (UL), 925 to 960 MHz (DL) n12: 699 to 716 MHz (UL), 729 to 746 MHz (DL) n20: 832 to 862 MHz (UL), 791 to 821 MHz (DL) n28: 703 to 748 MHz (UL). 758 to 803 MHz (DL) n41: 2496 to 2690 MHz (UL/DL) n66: 1710 to 1800 MHz (UL). 2110 to 2200 MHz (DL) n77: 3300 to 4200 MHz (UL/DL) n78: 3300 to 3800 MHz (UL/DL) n79: 4400 to 5000 MHz (UL/DL)



Wireless protocol standards	5GNR Air Interface 3GPP Rel15 5G NR sub-6 LTE Rel14 20 layers and 2 Gbps downlink (DL) throughput – 4 × 4 MIMO across 5x CA 200 Mbps uplink (UL) throughput – 40 MHz ULCA and 256 QAM WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification
GPS	Standalone, A-GPS (MS-A, MS-B)
GPS bands	GPS: L1 (1575.42MHz) GLONASS: L1 (1602MHz) BeidouB1(1561.098MHz) Galileo E1 (1575.42)
Maximum data rates	5G sub 6G : 3.8 Gbps LTE: ue-CategoryDL 20, (DL: 2 Gbps) ue-CategoryUL 18, (UL: 200Mbps) DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload)
Maximum output power	LTE: 23 dBm in all band except B41 LTE B41 HPUE = 26dBm HSPA+: 23.5 dBm
Maximum power consumption	5G Sub 6 : 2500 mA LTE: 1,300 mA (peak); 1100 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average)
Form Factor	M.2, 3042-S3 Key B
Weight	8 g
Dimensions (Length x Width x Thickness)	42 mm × 30 mm × 2.6 mm

 5G module is an optional feature that must be configured at purchase. AT&T and T-Mobile networks supported in the U.S. Module designed for 5G networks as carriers deploy Evolved-Universal Terrestrial Radio Access New Radio Dual Connectivity (ENDC) with both 100Mhz of 5G NR and LTE channel bandwidth, using 256QAM 4x4 as defined by 3GPP, requires activation and separately purchased service contract. Check with service provider for coverage and availability in your area. Connection, upload and download speeds will vary due to network, location, environment, network conditions, and other factors. 5G not available on all products, in all regions. Backwards compatible to 4G LTE and 3G HSPA technologies. 5G module planned to be available in select countries, where carrier supported.



Intel® XMM™ 7360 LTE- Advanced CAT9 ¹	Technology/Operating bands	FDD LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3), 1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 1400 (Band 11), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 17 lower), 850 (Band 18 lower), 850 (Band 19 upper), 800 (Band 20), 1400 (Band 21), 850 (Band 26), 700 (Band 28), 700 (Band 29 RX only), 2300 (Band 30), 1700/2100 (Band 66). TDD LTE: 2600 (Band 38), 1900 (Band 39), 2400 (Band 40), 2500 (Band 41). HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4), 850 (Band 5), 900 (Band 8) MHz
	Wireless protocol standards	3GPP Release 11 LTE Specification CAT.9, MAX 60MHz aggregation BW WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification
	GPS	Standalone, A-GPS (MS-A, MS-B)
	GPS bands	GPS 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou 1561.098 ± 2.046 MHz
	Maximum data rates	LTE: 450 Mbps (DL 3CA), 50 Mbps (Upload) DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload)
	Maximum output power	LTE: 23 dBm HSPA+: 23.5 dBm
	Maximum power consumption	LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average)
	Form Factor	M.2, 3042-S3 Key B
	Weight	6.2 g
	Dimensions (Length x Width x Thickness)	42 x 30 x 2.3 mm

1. Mobile Broadband is an optional feature. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.



Technical Specifications NXP NPC300 Near Field Dimensions (L x W x H) Communication Module

Module 17 mm by 10 mm by 2.0 mm Chipset NPC300 System interface 12C NFC RF standards ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 ISO/IEC 18092 ECMA-340 NFCIP-1 Target and Initiator ECMA-320 NFCIP-2 **NFC Forum Support** Tag Type 1, Type 2, Type3 and Type 4, NFCIP-1 and NFCIP-2 Reader (PCD-VCD) Mode¹ ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 MIFARE 1K **MIFARE 4K MIFARE DESFire** FeliCa Jewel and Topaz cards Card Emulation (PICC-ISO/IEC 14443 A VICC) Mode¹ ISO/IEC 14443 B and B' MIFARE FeliCa Frequency 13.56 MHz **NFC Modes Supported** Reader/Writer. Peer-to-Peer **Raw RF Data Rates** 106, 212, 424, 848 kbps 0°C to 70°C **Operating temperature** -20°C to 125°C Storage temperature Humidity 10-90% operating 5-95% non-operating Supply Operating 2.97 to 5.5 Volts voltage I/O Voltage 1.8V or 3.3V **Power Consumption** (Booster enable, VBAT= 3.3V, VCC_BOOST = 5V) Mode Power Consumption, Typical² Polling 7.3 mA **Detected Test Tag Type** 32.9 mA 1



Technical Specifications

Detected Test Tag Type 3	79.2 mA
Detected Test Tag Type 4	64.9 mA
Antenna	Antenna connector, 0.5mm pitch, 7 connector FPC. Antenna matching is external to module.

1. With application or UICC support

2. Actual Power Consumption is dependent on NFC antenna and matching circuit and on the particular polling sequence and period configured.



Technical Specifications

POWER

74 % at 115 Vac and 88.4 % at 230Vac · 63 Hz 1.4 A at 90 Vac
a. 1.4 A at 90 Vac
I
5V
at 115 Vac input
A
nm Barrel Type
F to 95°F (0°to 35°C)
to 185ºF (-20ºto 85ºC)
16,400 ft (0 to 5000m)
6 to 95%
6 to 95% Mark - full compliance with LVD and EMC directives orldwide safety standards - IEC60950-1 and/or IEC62368-1, 0950-1 and/or EN62368-1, UL60950-1 and/or UL62368-1 , Class1,
- // //

AC Adapter 45 Watt Dimensions Smart nPFC Standard Woight	95x40x26.8mm
Barrel 4,5mm Right	unit: 200g +/- 10g
Angle 1.0m 2prong	
Input Effici	
Input frequ	
Input AC cu Output	rent Max. 1.4 A at 90 Vac
Output pov	er 45W
DC output	19.5V
Hold-up tin	e 5ms at 115 Vac input
Output cur Connector	ent limit <8.0A
Connector	4.5mm Barrel Type
Environme	
Operating	mperature 32°F to 95°F (0°to 35°C)
Non-opera (storage) to	
Non-opera (storage) to	
Altitude	0 to 16,400 ft (0 to 5000m)
Humidity	20% to 95%
Storage Hu	
EMI and Sa Certificatio	ety Eg:
AC Adapter 65 Watt Dimensions	88x53.5x21mm
Straight 1.0m	unit: 220g +/- 10g
Input Effici	ncy 81.5% min at 115 Vac/ 230Vac @ 5V/3A 86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 12V/5A 89% min at 115 Vac/ 230Vac @ 15V/4.33A 89% min at 115 Vac/ 230Vac @ 20V/3.25A
Input frequ	ncv range 47 ~ 63 Hz
Input AC cu Output	
Output pov DC output	er 65W 5V/9V/12V/15V/20V



	Hold-up time Output current limit Connector	5ms at 115 Vac input <8.0A
	Connector Environmental Design Operating temperature	USB Type C
	Non-operating (storage) temperature	32ºFto 95ºF (Oºto 35ºC) -4ºFto 185ºF (-20ºto 85ºC)
	Non-operating (storage) temperature	
	Altitude Humidity Storage Humidity EMI and Safety Certifications	0 to 16,400 ft (0 to 5000m) 5% to 95% 5% to 95% Eg: *CE Mark - full compliance with LVD and EMC directives * Worldwide safety standards - IEC60950-1 and/or IEC62368-1, EN60950- 1 and/or EN62368-1, UL60950-1 and/or UL62368-1, Class1, SELV; Agency approvals - C-UL-US, DENAN, EN55032 Class B, FCC Class B, CISPR32 Class B, CCC, NOM-001 NYCE. * MTBF - over 200,000 hours at 25°C ambient condition.
AC Adapter 65 Watt nPFC Standard USB type C Straight 1.0m	Dimensions Weight Input Input Efficiency	90.0x51x28.5mm unit: 250g +/- 10g 81.5% min at 115 Vac/ 230Vac @ 5V/3A 86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 9V/3A 89% min at 115 Vac/ 230Vac @ 15V/4.33A 89% min at 115 Vac/ 230Vac @ 20V/3.25A
	Input frequency range Input AC current Output	47 ~ 63 Hz 1.6 A at 90 VAC and maximum load
	Output power DC output Hold-up time Output current limit	65W 5V/9V/12V/15V/20V 5ms at 115 Vac input 8.0A Max.
	Connector Connector Environmental Design Operating temperature	USB TYPE C 32°F to 95°F (0°to 35°C)
	Non-operating (storage) temperature	-4°F to 185°F (-20°to 85°C)



	Non-operating (storage) temperature	
	Altitude	0 to 16,400 ft (0 to 5000m)
	Humidity	20% to 95%
	Storage Humidity	10% to 95%
	EMI and Safety Certifications	Eg: *CE Mark - full compliance with LVD and EMC directives * Worldwide safety standards - IEC60950-1 and/or IEC62368-1, EN60950-1 and/or EN62368-1, UL60950-1 and/or UL62368-1, Class1, SELV; Agency approvals - C-UL-US, DENAN, EN55032 Class B, FCC Class B, CISPR32 Class B, CCC, NOM-001 NYCE. * MTBF - over 200,000 hours at 25°C ambient condition.
AC Adapter 65 Watt	Dimensions	102x55x30mm
Smart nPFC EM Barrel	Weight	unit: 250g +/- 10g
4.5mm New EM	Input	
	Input Efficiency	88.0 % at 115 Vac and 89.0 % at 230Vac
	Input frequency range	47 ~ 63 Hz
	Input AC current Output	Max. 1.7 A at 90 Vac
	Output power	65W
	DC output	19.5V
	Hold-up time	5ms at 115 Vac input
	Output current limit Connector	<11.0A
	Connector	4.5mm Barrel Type
	Environmental Design	
	Operating temperature	32ºF to 95ºF (0ºto 35ºC)
	Non-operating (storage) temperature	-4ºF to 185ºF (-20ºto 85ºC)
	Non-operating (storage) temperature	
	Altitude	0 to 16,400 ft (0 to 5000m)
	Humidity	20% to 95%
	Storage Humidity	10% to 95%
	EMI and Safety Certifications	Eg: *CE Mark - full compliance with LVD and EMC directives * Worldwide safety standards - IEC60950-1 and/or IEC62368-1, EN60950-1 and/or EN62368-1, UL60950-1 and/or UL62368-1, Class1, SELV; Agency approvals - C-UL-US, DENAN, EN55032 Class B, FCC Class B, CISPR32 Class B, CCC, NOM-001 NYCE. * MTBF - over 200,000 hours at 25°C ambient condition.



AC Adapter 65 Watt Smart nPFC Standard Barrel 4.5mm Right Angle 1.0m	Dimensions Weight Input	90x51x28.5mm unit: 230g +/- 10g
	Input Efficiency	88.0 % at 115 Vac and 89.0 % at 230Vac
	Input frequency range	47 ~ 63 Hz
	Input AC current Output	Max. 1.7 A at 90 Vac
	Output power	65W
	DC output	19.5V
	Hold-up time	5ms at 115 Vac input
	Output current limit Connector	<11.0A
	Connector	4.5mm Barrel Type
	Environmental Design	
	Operating temperature	32°F to 95°F (0°to 35°C)
	Non-operating (storage) temperature	-4°F to 185°F (-20°to 85°C)
	Non-operating (storage) temperature	
	Altitude	0 to 16,400 ft (0 to 5000m)
	Humidity	20% to 95%
	Storage Humidity	10% to 95%
	EMI and Safety Certifications	Eg: *CE Mark - full compliance with LVD and EMC directives * Worldwide safety standards - IEC60950-1 and/or IEC62368-1, EN60950-1 and/or EN62368-1, UL60950-1 and/or UL62368-1, Class1, SELV; Agency approvals - C-UL-US, DENAN, EN55032 Class B, FCC Class B, CISPR32 Class B, CCC, NOM-001 NYCE. * MTBF - over 200,000 hours at 25°C ambient condition.

Technical Specifications

Battery CC 3 Cell 53 Wh ¹ 53 Long Life -PL Fast	Dimensions (H x W x L) Weight	7.3 x 52.9 x 267.11mm (0.287 x 2.082 x 10.516 inch) 0.205 kg (0.45 lb)
Charge	Cells/Type	3cell Lithium-Ion Polymer cell
	Energy	
	Voltage	11.55V
	Amp-hour capacity	4.59Ah
	Watt-hour capacity ¹	53Wh
	Temperature	
	Operating (Charging)	32° to 113° F (0° to 45° C)
	Operating (Discharging)	14° to 140° F (-10° to 60° C)
	Fuel Gauge LED	N/A
	Warranty	Depends on system offering
	Optional Travel Battery Available	No

1. Actual battery Watt-hours (Wh) will vary from design capacity. Battery capacity will naturally decrease with shelf life, time, usage, environment, temperature, system configuration, loaded apps, features, power management settings and other factors.

FINGERPRINT READER

Model: Synaptics Validity VFS7604 touch sensor Mobile Voltage Operation: 3.0V to 3.6V **Operating Temperature:** 0~60°C **Current Consumption Image:** 100mA Max Low Latency Wait For Finger: 260 uA Capture Rate: <30msec per image **ESD** Resistance: IEC 61000-4-2 4B (+/-15KV) **Detection Matrix:** 363 dpi / 7.4x6mm sensor area FRR (False Reject Rate) / FAR (False Acceptance Rate):

FRR <1% @ 1:50K FAR



ENVIRONMENTAL DATA

Eco-Label Certifications &	This product has received	or is in the process of beir	g certified to the following approvals and may	
declarations	be labeled with one or more of these marks:			
Sustainable Impact Specifications	 IT ECO declaration US ENERGY STAR[®] US Federal Energy Management Program (FEMP) EPEAT^O Gold registered in the United States. See http://www.epeat.net for registration status in your country. TCO certified China Energy Conservation Program (CECP) China State Environmental Protection Administration (SEPA) Taiwan Green Mark Korea Eco-label Japan PC Green label* Ocean-bound plastic in Speaker box 30% post-consumer recycled plastic External Power Supply 90% Efficiency Low halogen Outside Box and corrugated cushions are 100% sustainably sourced and recyclable Molded Paper Pulp Cushion inside box is 100% sustainably sourced and recyclable 			
	Bulk packaging available			
System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a "Typically Configured Notebook".			
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz	
Normal Operation (Sort idle)	6.36 W	6.53 W	6.61 W	
Normal Operation (Long idle)	1.25 W	1.15 W	1.11 W	
Sleep	1.25 W	1.15 W	1.11 W	
Off	0.29 W	0.31 W	0.29 W	
	family. HP computers mar Environmental Protection family does not offer ENE	ked with the ENERGY STA Agency (EPA) ENERGY ST RGY STAR® compliant conf PC featuring a hard disk	⁹ compliant product if offered within the model R [®] Logo are compliant with the applicable U.S. TAR [®] specifications for computers. If a model igurations, then energy efficiency data listed is the drive, a high efficiency power supply, and a	



Heat Dissipation*	115VAC	C, 60Hz 230VAC		, 50Hz		100VAC, 50Hz
Normal Operation (Short idle)	22 BT	U/hr 22 BTU		U/hr		23 BTU/hr
Normal Operation (Long idle)	4 BTI	J/hr	4 BTU	J/hr		4 BTU/hr
Sleep	4 BTI	J/hr	4 BTU	J/hr		4 BTU/hr
Off	1 BTI	J/hr	1 BTU	J/hr	1 BTU/hr	
	*NOTE: Heat attained for o	•	s calculated ba	sed on the m	easured watts, a	ssuming the service level is
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)		Sound Power (L _{WAd} , bels)	r		Sound P (L _{pAm} , de	
Typically Configured – Idle		2.5			15	.8
Fixed Disk – Random writes	2.5		24.4			
Optical Drive – Sequential reads	2.7			15.5		
Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the spare parts are available throughout the warranty period and or for up to "5" years after the end of					
	spare parts production.					
Additional Information	 This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive - 2002/96/EC. This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold level, see http://www.epeat.net Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. This product is 95.2% recycle-able when properly disposed of at end of life. 					
Packaging Materials	External:	PAPER/Cor	rugated			41 g
	Internal:	PAPER/Mo				163 g
			olyethylene low	<i>i</i> density		14 g
	PAPER/paperboard 220 g					
	The plastic packaging material contains at least 0% recycled content. The corrugated paper packaging materials contains at least 0% recycled content.					
	The corruga	ted paper pa	ckaging materia	als contains al	ieast 0% recycle	ea content.



RoHS Compliance	 HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam. We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances—including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products. We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to
	evolve.
	To obtain a copy of the HP RoHS Compliance Statement, see HP RoHS position statement.
Material Usage	This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html):
	 Asbestos Certain Azo Colorants Certain Brominated Flame Retardants – may not be used as flame retardants in plastics Cadmium Chlorinated Hydrocarbons Chlorinated Paraffins Bis(2-Ethylhexyl) phthalate (DEHP) Benzyl butyl phthalate (BBP) Dibutyl phthalate (DBP) Diisobutyl phthalate (DBP) Diisobutyl phthalate (DBP) Diisobutyl phthalate (DBP) Formaldehyde Halogenated Diphenyl Methanes Lead carbonates and sulfates Lead carbonates and sulfates Lead and Lead compounds Mercuric Oxide Batteries Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. Ozone Depleting Substances Polybrominated Biphenyl Ethers (PBBEs) Polybrominated Biphenyl Oxides (PBBOs) Polychlorinated Biphenyl (PCB) Polychlorinated Terphenyls (PCT) Polychlorinated Ferphenyls (PCT) Polychlorinated Ferphenyls (PCT) Polychlorinated Section (TPT), Tributyl Tin Oxide (TBTO)



Packaging Usage	 HP follows these guidelines to decrease the environmental impact of product packaging: Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. Eliminate the use of ozone-depleting substances (ODS) in packaging materials. Design packaging materials for ease of disassembly. Maximize the use of post-consumer recycled content materials in packaging materials. Use readily recyclable packaging materials such as paper and corrugated materials. Reduce size and weight of packages to improve transportation fuel efficiency. Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	HP offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.
	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.
HP, Inc. Corporate	For more information about HP's commitment to the environment:
Environmental	
Information	Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications
	http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates:
	http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842
	and
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf
footnotes	 Percentage of ocean-bound plastic contained in each component varies by product Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard. External power supplies, WWAN modules, power cords, cables and peripherals excluded. 100% outer box packaging and corrugated cushions made from sustainably sourced certified and recycled fibers. Fiber cushions made from 100% recycled wood fiber and organic materials. Plastic cushions are made from >90% recycled plastic.

COUNTRY OF ORIGIN

China



Options and Accessories (sold separately and availability may vary by country)

Category	Description	Part Number
Cases	HP Exec 15.6 Backpack	6KD07AA
	HP Exec 15.6 Top Load Case	6KD06AA
	HP Executive Slim 14.1 Top Load Case	6KD04AA
		2UK37AA
Docking	HP Thunderbolt Dock 120W G2	3TR87AA
	HP TB Dock w/ Combo Cable (230W)	3YE87AA
	HP Thunderbolt 120W Dock w/Audio G2	1PM64AA
	HP USB-C Mini Dock	5TW10AA
	HP USB-C Dock G5	5TW13AA
	HP USB-C/A Universal Dock G2	JIWIJAA
Input/Output	HP Wireless Rechargeable 950MK Mouse and Keyboard	3M165AA
	HP Wireless Premium Keyboard	Z9N41AA
	HP Bluetooth Fingerprint Reader USB Mouse	4TS44AA
	HP Comfort Grip Wireless Mouse	H2L63AA
	HP X4000b Bluetooth Mouse	H3T50AA
	HP USB Travel Mouse	G1K28AA
	HP Bluetooth Travel Mouse	6SP30AA
	HP Wireless Premium Mouse	1JR31AA
	HP USB Premium Mouse	1JR32AA
	HP USB Laser 3 Button USB Mouse	H4B81AA
	HP Elite Presenter Mouse	2CE30AA
	HP Stereo USB Headset	T1A67AA
	HP WL USB Keyboard	T6U20AA
	HP Slim Wireless Keyboard and Mouse	T6L04AA
	HP 235 WL Mouse and Keyboard Combo	1Y4D0AA
	HP 125 Wired Keyboard	266C9AA
	HP 225 Wired Mouse and Keyboard Combo	286J4AA
	HP USB-C to VGA	N9K76AA
	HP HDMI to VGA	H4F02AA
	HP USB-C to HDMI 2.0 Adapter	1WC36AA
	HP USB-C to RJ45 Adapter HP USB to Gig RJ45 Adapter	V7W66AA N7P47AA
	HP USB-C Travel Hub G2	7PJ38AA
	HP Elite USB-C Hub	4WX89AA
Power	HP 45W USB-C LC Dali AC Power Adapter	1MZ01AA
	HP 45W USB-C Power Adapter	1HE07AA
	HP 65W USB-C Power Adapter	1HE08AA
	65W USB-C Slim Power Adapter	3PN48AA
	HP USB-C Essential Power Bank	3TB55AA



Options and Accessories (sold separately and availability may vary by country)

Memory	HP 4GB DDR4 3200 Memory HP 8GB DDR4 3200 Memory HP 16GB DDR4 3200 Memory	286H5AA 286H8AA 286J1AA
Security	HP Nano Keyed Cable Lock HP Sure Key Cable Lock	1AJ39AA 6UW42AA



Summary of Changes

Date of change:	Version History:	Updated	Description of change:
March 25, 2021	V1 to V2	Update	Battery Life
April 19,2021	V2 to V3	Updated	Memory Section and Input/ Output Section Updated
April 23, 2021	V3 to V4	Added	BIOS information in Software section
May 6, 2021	V4 to V5	Removed	Processors base frequency/Added HP Smart Support
May 20, 2021	V5 to V6	Removed	HP Thunderbolt Dock 230W G2
May 27, 2021	V6 to V7	Update	HP Pro Security Edition to HP Wolf Pro Security Edition
June 11, 2021	V7 to V8	Removed	HP WorkWell from Software and Security section
September 2, 2021	V8 to V9	Added	Environmental Data
September 7, 2021	V9 to V10	Updated	Techspecs in Networking, Storage and Power section
September 16, 2021	V10 to V11	Updated	Environmental Data
November 11, 2021	V11 to V12	Updated	Windows 10 with Free upgrade to Windows 11 when available in OS section and footnote.
December 9, 2021	V12 to V13	Updated	OS footnotes and Wi-Fi 6 footnotes
December 14, 2021	V13 to V14	Updated	Windows OS section

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